DAYA SEMICONDUCTOR

ABS1 THRU ABS10

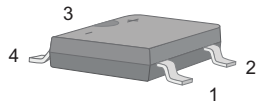
1.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1.0A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



ABS Package

MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg / 0.0031oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	ABS1	ABS2	ABS4	ABS6	ABS8	ABS10	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T_c = 125 °C	I_O	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	40						A
Forward Voltage per element @I_F=1.2A	V_F	1.0						V
Maximum DC Reverse Current @T_A=25 °C at Rated DC Blocking Voltage @T_A=125 °C	I_R	5 100						μA
Typical Junction Capacitance (Note1)	C_j	18						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$	70 18						°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Fig.1 Average Rectified Output Current Derating Curve

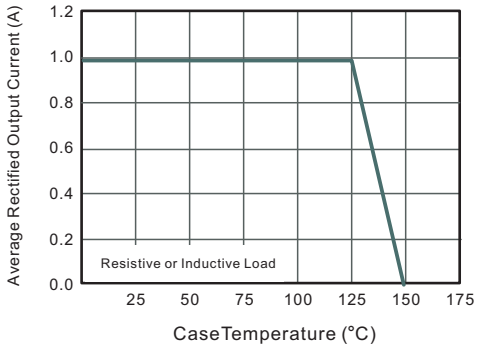


Fig.2 Typical Reverse Characteristics

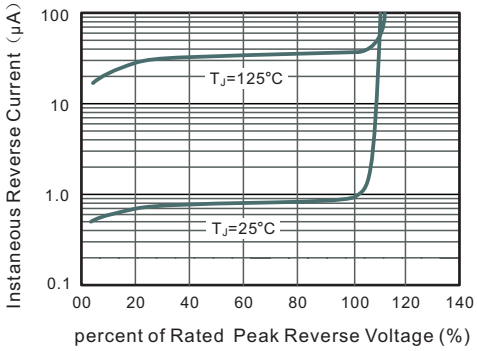


Fig.3 Typical Instaneous Forward Characteristics

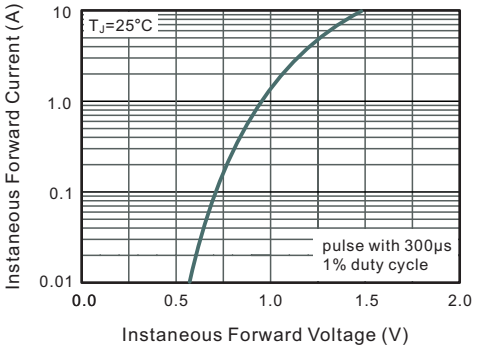


Fig.4 Typical Junction Capacitance

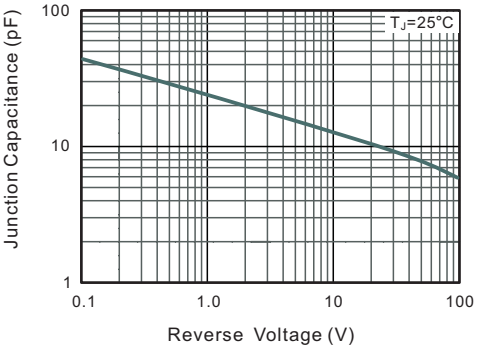
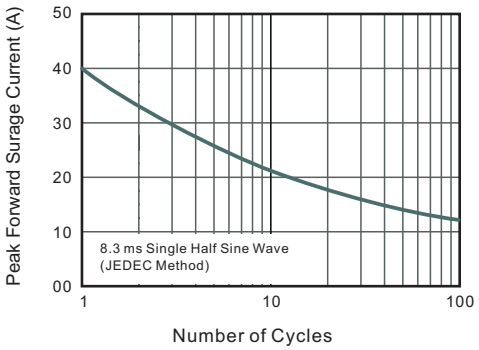
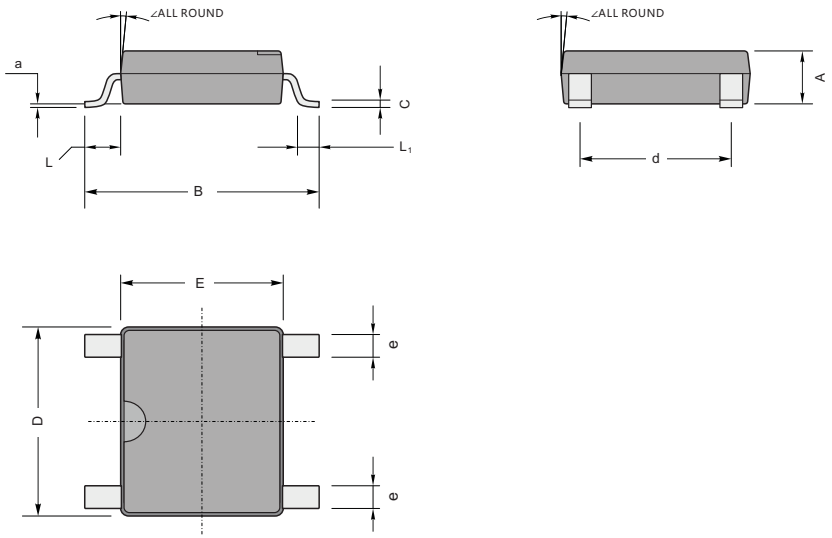


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current



PACKAGE OUTLINE

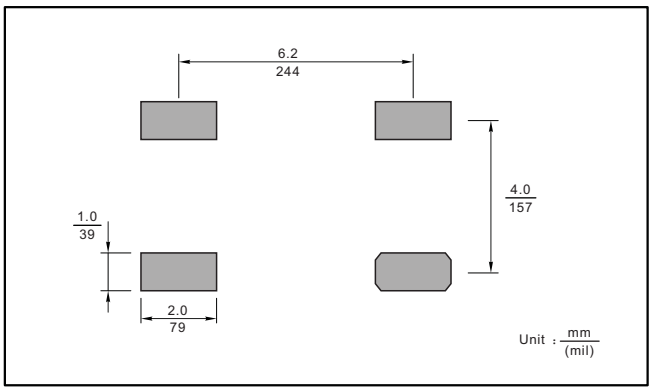
Plastic surface mounted package; 4 leads ABS



ABS/LBF mechanical data

UNIT		A	C	D	E	B	d	e	L	L_1	a	∠
mm	max	1.5	0.22	5.3	4.6	6.5	4.2	0.7	0.95	0.6	0.2	5°
	min	1.3	0.15	5.0	4.3	6.1	3.8	0.5				
mil	max	59	8.7	209	181	256	165	28	37	24	8	
	min	51	5.9	197	169	240	150	20				

The recommended mounting pad size



Marking

Type number	Marking code
ABS1	ABS1
ABS2	ABS2
ABS4	ABS4
ABS6	ABS6
ABS8	ABS8
ABS10	ABS10

